

REL61TO LEAD-FREE SOLDER TOP-OFF ALLOY

FEATURES

- For use with AIM REL61™ Alloy to Reduce Copper Levels
- Available in Solder Bar and Chunk
- Manufactured using AIM Electropure® Processes
- For use in Lead-Free Process Only

DESCRIPTION

AIM's REL61TO alloy is used to correct and maintain the copper content of REL61 alloy in wave and selective soldering applications. REL61TO is comprised of tin, bismuth, silver and micro-alloy elements.

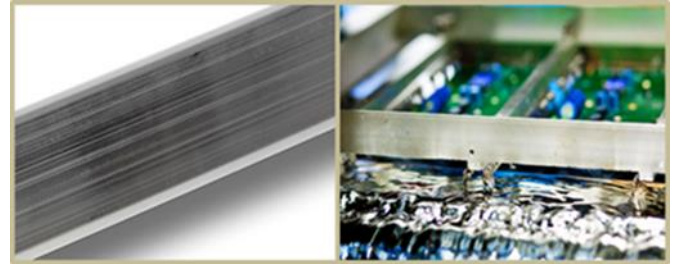
PROCESS

REL61 alloy copper levels may increase due to copper dissolved from PCB and components leads. Excess copper content can adversely impact the performance of REL61, increasing the incidence of bridges, icicles and other defects. Replenishing solder with REL61TO will maintain copper content at recommended levels. AIM Solder analysis should be performed monthly to monitor and control solder bath within specified limits.

SOLDER POT ANALYSIS

Take Action Limits (TAL)		
Ag: 1.5	Au: 0.2	Al: 0.06
As: 0.03	Bi: 3.2	Cd: 0.01
Cu: 1.2	Fe: 0.05	Ni: 0.1
Pb: 0.1	Sb: 0.5	Zn: 0.006

Take Action Limits (TAL) are intended to provide users with upper limits of alloy impurities while material is in use. TAL are established by AIM and are IPC J-STD-001 compliant. These guidelines may be adjusted to achieve specific product performance requirements.



HANDLING & STORAGE

Parameter	Time	Temperature
Shelf Life	Indefinite	Room Temperature

Solid alloy solder products have an indefinite shelf life when proper storage conditions are observed. Consult the SDS for specific handling procedures.

AVAILABILITY

REL61TO is available in bar and solder chunk. Other formats may be available upon request.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying SDS for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.